

# HSF

**NOTES:**

- 1.Current Rating:2A Max (only one pin) ;
- 2.Voltage Rating:175V DC;
- 3.Contact Resistance:30mΩ Max;
- 4.Withstand Voltage:675V AC;
- 5.Insulation Resistance:5000MΩ Min;
- 6.Operating Temperature: -55°C to +125°C;
- 7.Insulator Material: LCP,G.F,UL94V-0,BK;
- 8.Contact Material:Copper Alloy;
- 9.Contact plating:  
 Au on contact area (See ordering information),  
 100μ" Matte TIN on solder area,  
 50μ" Nickel underplating overall;
- 10.Recommended process:  
 Wavesolder,Peak temperature:260±5°C, 5s ;

## Ordering Information

37 2 0 X- S M XXX XXX XX X XX

**OPTIONS**

- 1=A
- 2=LC
- 3=FL
- S=SOCKET
- M=180° SMT

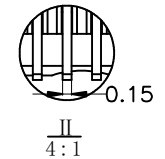
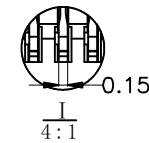
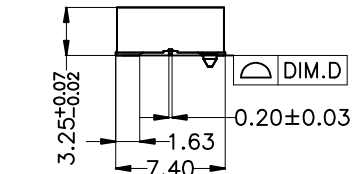
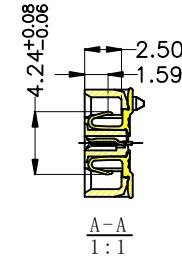
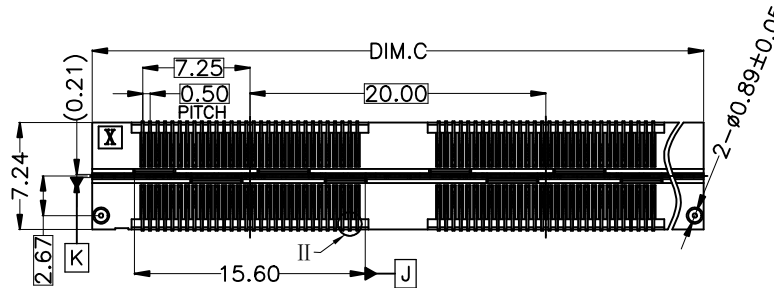
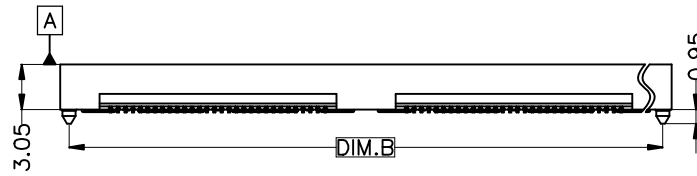
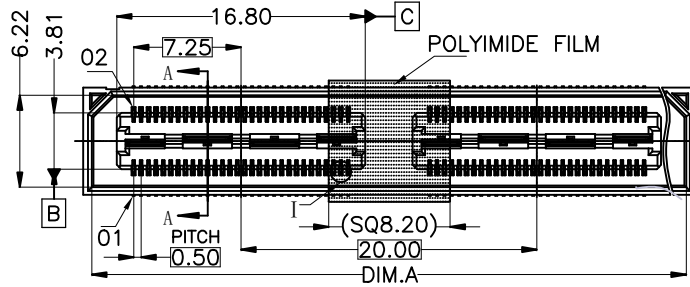
**No of POSITIONS**

- 060=60PIN
- 120=120PIN
- 180=180PIN
- 240=240PIN
- 300=300PIN

**LEAD STYLE**

- 032=3.25

- WCON INTERNAL CODE
- PACKAGING  
 A=VACUUM BOX  
 R=TAPE&REEL
- PLATING  
 W1=SEL.3U"GOLD/MATTE SN  
 W3=SEL.10U"GOLD/MATTE SN  
 W5=SEL.30U"GOLD/MATTE SN



REV	DATE	MODIFICATION DESCRIPTION	CHANGE	OPERATION	DRAW	DATE	SCALE	Fit	PART NO.
A0	2022.04.06	NEW		x.x ±0.40	Abt Chen	2022.04.06	UNIT	mm	RH-37203-SMXXX-032XXX01
				x.xx ±0.25	CHECK	DATE	SIZE	A4	TITLE:
				x.xxx ±0.15	APPROVE	DATE	SHEET	1/4	0.5mmB0 TO B0 SOCKET SMT, H=3.25, ASSEMBLY
				Angle ± 3°			PROJ.		Customer NO.
				DIM TOL					



<https://www.renhotec.com>

info@renhotec.com